

R&D VaporTech Vapor Reflow Oven

The RD2 provides consistent, uniform, and reliable heat transfer for high quality reflow. With a working envelope of 18" L (455 mm) x 15" W (380 mm) x 2.5" H (63 mm), the RD2 features a patented palletized conveyor system that keeps the product horizontal throughout the process.

RD2 Vapor phase reflow oven: The reflow oven provides a large envelope for solder reflow and is perfectly suited for the development of 3D Heterogenous Microsystems beyond what can be achieved with standard conveyor reflow furnaces.

1. Solder reflow envelope: 455mm x 380mm x 63mm
2. Reflow temperature range: 200°C to 320°C
3. Inert fluid capacity: 3 Gallons
4. Charge: \$60/hour (academic)



Power Requirements: The RD2 requires the following power to operate correctly. The facilities are available in HiDEC's Wavemat room where the tool was installed when originally purchased.

1. Power: 208 VAC, 3 phase, 63 Amps, 60 Hz
2. Main heater: 12.5kW
3. Preheat: 6kW



Facility requirements: Just add cooling water and possibly exhaust.

1. Process chill water: 3 to 5 gallons per minute (25°C to 40°C)



Operation: Very simple operation an example of which can be found on YouTube:

1. <https://youtu.be/QajgaN62DxA>

